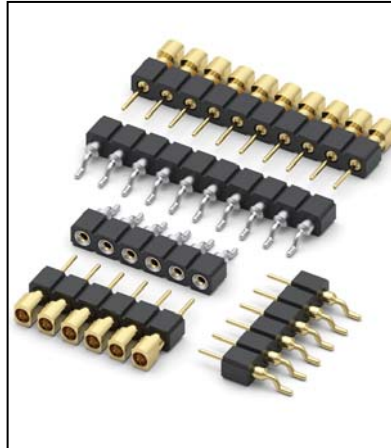


MAXIMUM SOLUTIONS

Horizontal SMT Z-Bend Socket and Headers .050" and .100" Grids



For low profile IO applications, these surface mount SIP socket and header strips are assembled parallel to their board surface. They are ideal for placement near the board edge for easy access test connections and creating pluggable adapter modules which can sit perpendicular to the motherboard (mated to a vertical connector,) effectively conserving precious board real estate. Mill-Max offers a choice between .050" (1,270 mm) and .100" (2,540 mm) grid horizontal Z-Bend sockets and headers.

The 310, .100" (2,540 mm) grid, horizontal Surface Mount Z-Bend Sockets use MM #1023 receptacles that accept pin diameters from .015" - .025" (0,381 - 0,635 mm.) These sockets are rated 3 amps per position. Series 801, .100" (2,540 mm) grid, uses MM #1303 receptacles that accept pin diameters from .025" - .037" (0,635 - 0,940 mm) and .025" (0,635 mm) square leads. These sockets are rated at 4.5 amps per pin position.

Standard configurations are available from 2-10 positions with a .005" (0,127 mm) co-planarity rating. They come packaged in tubes. A tape and reel option can be quoted upon request. Note: The socket is available in longer strip configurations, but co-planarity will need to be determined.

Series 850, .050" (1,270 mm) grid horizontal SMT Z-Bend Headers are available with .016" (0,406 mm) diameter solder tails and pluggable pins, using MM #4006-1 pins. Series 851 horizontal SMT Z-Bend sockets use MM #4890-1 receptacles that accept pin diameters from .015" - .020" (0,381 - 0,508 mm.) These headers are rated at 3 amps per pin position. Standard configurations are 2-20 positions with a .005 (0,127 mm) coplanarity rating.

For more information, visit www.mill-max.com/PR572.

INTERCONNECTS

SERIES 850 & 851 • .050" GRID HORIZONTAL SURFACE MOUNT Z-BEND HEADERS & SOCKETS • SINGLE ROW STRIPS

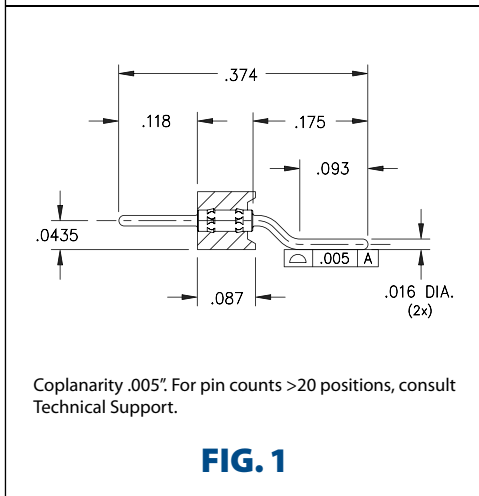
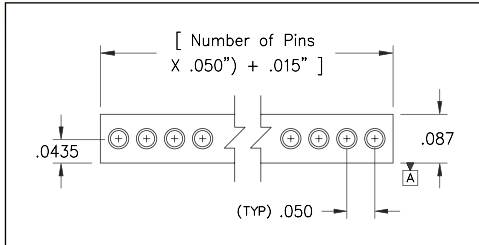


FIG. 1

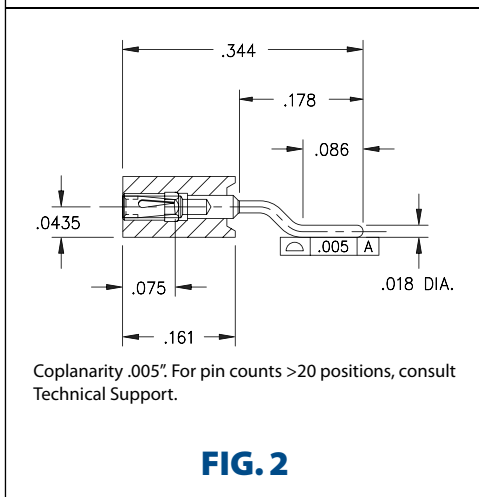
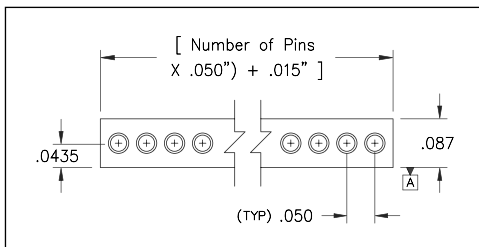
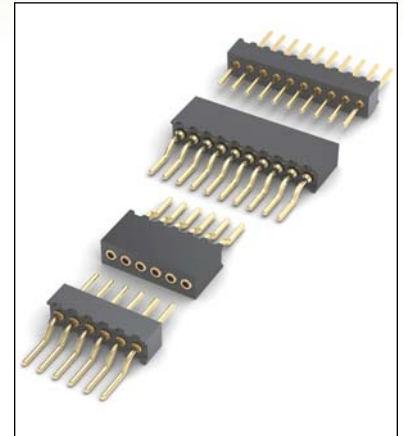


FIG. 2

- Series 850 horizontal surface mount headers have .016" dia. pluggable pins and Z-bend tails for SMT soldering to the P.C.B. (MM #4006-1). See page 208 for details
- Series 851 horizontal Surface Mount Z-Bend sockets uses MM #4890-1 receptacles that accept pin diameters from .015"-.020". See page 160 for details
- Receptacles use Hi-Rel, 3-finger BeCu #11 contact rated at 3 amps. See page 251 for details
- Insulators are high temperature thermoplastic, suitable for all soldering operations



ORDERING INFORMATION

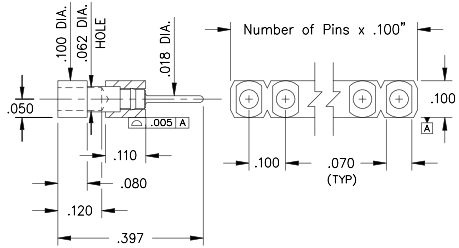
FIG. 1	Series 850...001 Single Row Surface Mount Z-Bend Header					
	850-10-0-40-001000 Specify number of pins 02-20					
SPECIFY PLATING CODE XX=		10				
Pin Plating		10 μ" Au				
FIG. 2	Series 851...001 Single Row Surface Mount Z-Bend Socket					
	851-XX-0-40-001000 Specify number of pins 02-20					
SPECIFY PLATING CODE XX=		11	13			
Sleeve (Pin)		10 μ" Au	10 μ" Au			
Contact (Clip)		10 μ" Au	30 μ" Au			



INTERCONNECTS

SERIES 310, 330, 351 • .100" GRID (.018" DIA. PINS), SURFACE MOUNT HEADERS AND SOCKETS • SINGLE ROW STRIPS

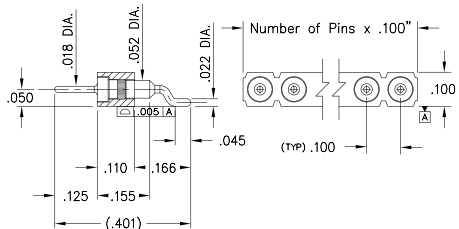
Mates with Series 310...023 Surface Mount Z-Bend Socket (See Fig. 3)



Coplanarity .005". For pin counts >10 positions, consult Technical Support.

FIG. 1

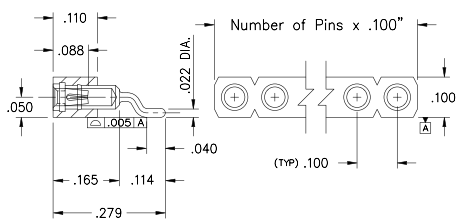
Mates with Series 310...023 Surface Mount Z-Bend Socket (See Fig. 3)



Coplanarity .005". For pin counts >10 positions, consult Technical Support.

FIG. 2

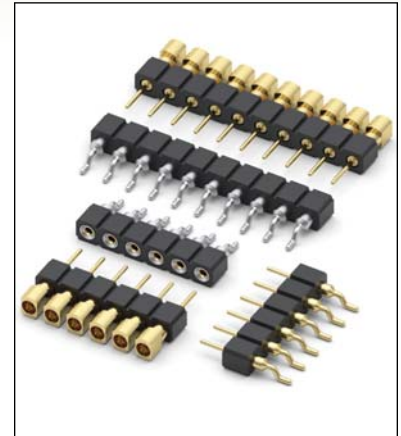
Mates with Series 351...002 and 330...027 Surface Mount Header (See Fig. 1 & 2)



Coplanarity .005". For pin counts >10 positions, consult Technical Support.

FIG. 3

- Series 351 horizontal surface mount headers are available with .018" dia. pluggable pins (MM #5102). Series 330 horizontal surface mount z-bend headers use MM #3027 pins. See page 224 for details
- Series 310 horizontal surface mount Z-Bend sockets uses MM #1023 receptacles that accept pin diameters from .015"-.025". See pages 171 for details
- Insulators are high temperature thermoplastic, suitable for all soldering operations
- Ideal for daisy chaining parallel boards



ORDERING INFORMATION















FIG. 1	Series 351...002 .018" Dia. Surface Mount Header
	351-10-1__-40-002000 Specify number of pins 02-10
FIG. 2	Series 330...027 .018" Dia. Surface Mount Z-Bend Header
	330-XX-1__-40-027000 Specify number of pins 02-10
  	
SPECIFY PLATING CODE XX=	10  40 
Pin Plating 	10 μ" Au 200 μ" Sn

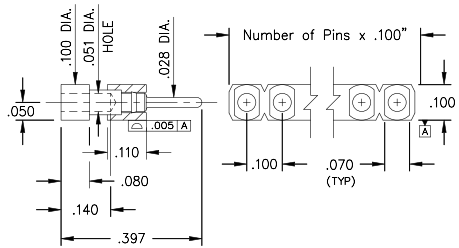
FIG. 3	Series 310...023 .018" Dia. Surface Mount Z-Bend Socket
	310-XX-1__-40-023000 Specify number of pins 02-10
  	
SPECIFY PLATING CODE XX=	91 93 99 41  43  44 
Sleeve (Pin) 	200 μ" Sn/Pb 200 μ" Sn/Pb 200 μ" Sn/Pb 200 μ" Sn 200 μ" Sn 200 μ" Sn
Contact (Clip) 	10 μ" Au 30 μ" Au 100 μ" Sn/Pb 10 μ" Au 30 μ" Au 100 μ" Sn



INTERCONNECTS

SERIES 800, 801, 830 • .100" GRID (.030" DIA. PINS), SURFACE MOUNT HEADERS AND SOCKETS • SINGLE ROW STRIPS

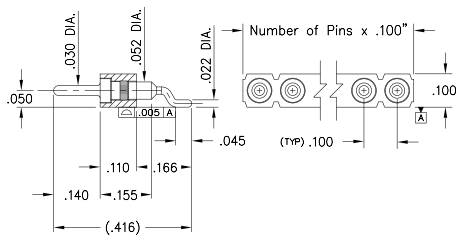
Mates with Series 801...002 Surface Mount Z-Bend Socket (See Fig. 3)



Coplanarity .005". For pin counts >10 positions, consult Technical Support.

FIG. 1

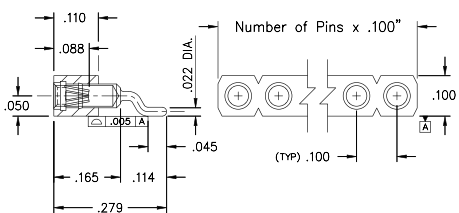
Mates with Series 801...002 Surface Mount Z-Bend Socket (See Fig. 3)



Coplanarity .005". For pin counts >10 positions, consult Technical Support.

FIG. 2

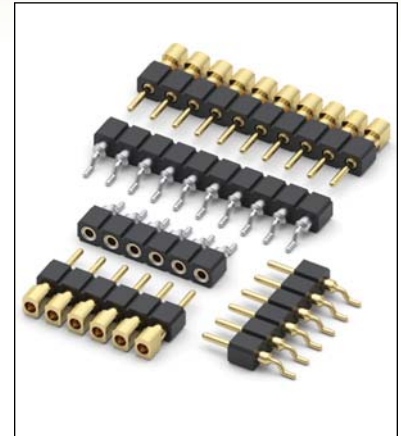
Mates with Series 800...002 and 830...028 Surface Mount Header (See Fig. 1 & 2)



Coplanarity .005". For pin counts >10 positions, consult Technical Support.

FIG. 3

- Series 800 horizontal surface mount headers are available with .028" dia. pluggable pins (MM #1502). Series 830 horizontal surface mount z-bend headers use MM #3028 pins. See page 224 for details
- Series 801 horizontal surface mount Z-Bend sockets uses MM #1303 receptacles that accept pin diameters from .025"-.037" and .025" square leads. See pages 180 for details
- Insulators are high temperature thermoplastic, suitable for all soldering operations
- Ideal for daisy chaining parallel boards



ORDERING INFORMATION



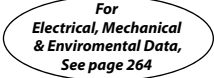





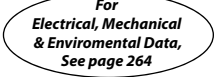





FIG. 1	Series 800...002 .028" Dia. Surface Mount Header
	800-10-0-40-002000 Specify number of pins 02-10
FIG. 2	Series 830...028 .030" Dia. Surface Mount Z-Bend Header
	830-XX-0-40-028000 Specify number of pins 02-10
  	
SPECIFY PLATING CODE XX=	10  40 
Pin Plating 	10 μ" Au 200 μ" Sn

FIG. 3	Series 801...002 .028" Dia. Surface Mount Z-Bend Socket
	801-XX-0-40-002000 Specify number of pins 02-10
  	
SPECIFY PLATING CODE XX=	91 93 99 41  43  44 
Sleeve (Pin) 	200 μ" Sn/Pb 200 μ" Sn/Pb 200 μ" Sn/Pb 200 μ" Sn 200 μ" Sn 200 μ" Sn
Contact (Clip) 	10 μ" Au 30 μ" Au 100 μ" Sn/Pb 10 μ" Au 30 μ" Au 100 μ" Sn

